

IN THE SPECIFICATION

Please amend the Title on page 1 as follows:

~~MEMORY CHIP AND SEMICONDUCTOR DEVICE USING THE MEMORY~~  
~~CHIP AND MANUFACTURING METHOD OF THOSE~~ A CHIP ON CHIP DEVICE  
INCLUDING BASIC CHIPS CAPABLE OF FUNCTIONING INDEPENDENTLY FROM  
EACH OTHER, AND A SYSTEM IN PACKAGE DEVICE INCLUDING THE CHIP ON  
CHIP DEVICE